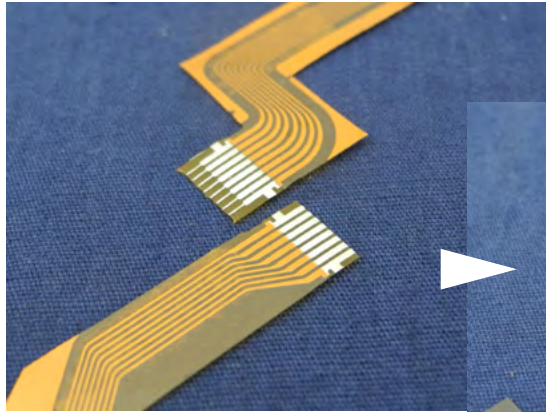




# SoundBonding application

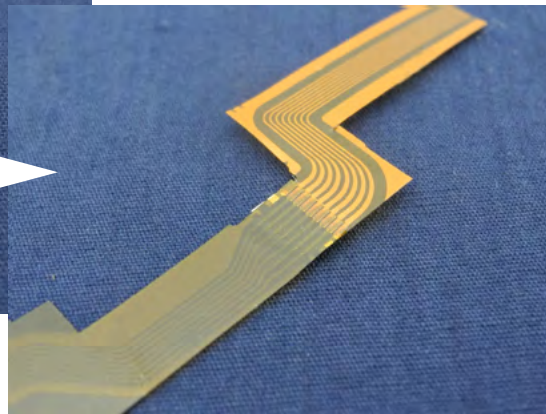


## <FPC Clip Ingot Bonding>

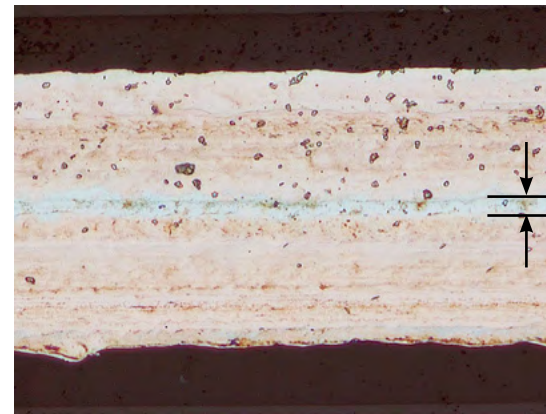


[Before]

- Copper circuit : about 50  $\mu\text{m}$  thick
- Solder plate : 10  $\mu\text{m}$  thick

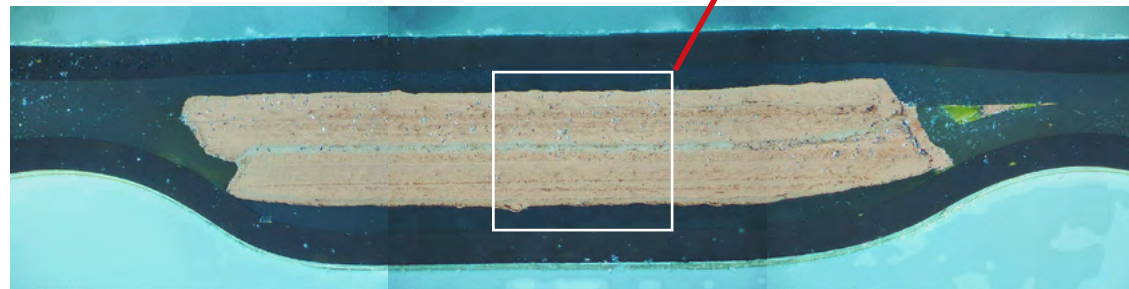


[After]



[Expanded x1750]

- Bonded Solder plate about 6.5  $\mu\text{m}$  thick



[Bonded area cross section]